# P-Channel 1.2-V (G-S) MOSFET

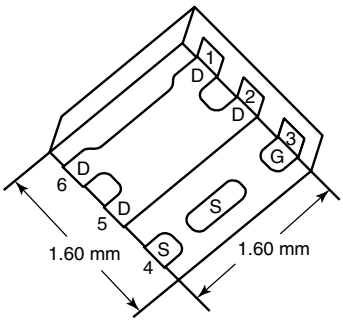
| PRODUCT SUMMARY | | | |
|---|---|---|---|
| $V_{DS}$ (V) | $R_{DS(on)}$ (Ω) | $I_D$ (A) | $Q_g$ (Typ.) |
| - 8 | 0.058 at $V_{GS}$ = - 4.5 V | - 9.0[a] | 7.3 nC |
| | 0.080 at $V_{GS}$ = - 2.5 V | - 9.0[a] | |
| | 0.100 at $V_{GS}$ = - 1.8 V | - 4.0 | |
| | 0.130 at $V_{GS}$ = - 1.5 V | - 2.0 | |
| | 0.250 at $V_{GS}$ = - 1.2 V | - 0.5 | |

## FEATURES

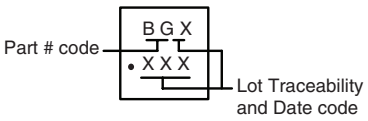
- **Halogen-free According to IEC 61249-2-21 Definition**
- TrenchFET® Power MOSFET
- New Thermally Enhanced PowerPAK® SC-75 Package
  - Small Footprint Area
  - Low On-Resistance
- 100 % $R_g$ Tested
- Typical ESD Protection 900 V
- Compliant to RoHS Directive 2002/95/EC

Pb-free
RoHS COMPLIANT
HALOGEN FREE

**PowerPAK SC-75-6L-Single**

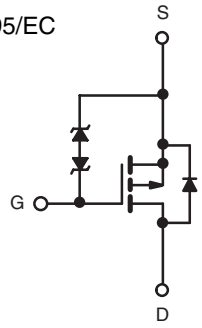



**Marking Code**




## APPLICATIONS

- Load Switch for Portable Devices




P-Channel MOSFET

**Ordering Information:** SiB417EDK-T1-GE3 (Lead (Pb)-free and Halogen-free)

| ABSOLUTE MAXIMUM RATINGS $T_A$ = 25 °C, unless otherwise noted | | | | |
|---|---|---|---|---|
| **Parameter** | | **Symbol** | **Limit** | **Unit** |
| Drain-Source Voltage | | $V_{DS}$ | - 8 | V |
| Gate-Source Voltage | | $V_{GS}$ | ± 5 | |
| Continuous Drain Current ($T_J$ = 150 °C) | $T_C$ = 25 °C | $I_D$ | - 9[a] | A |
| | $T_C$ = 70 °C | | - 9[a] | |
| | $T_A$ = 25 °C | | - 5.8[b, c] | |
| | $T_A$ = 70 °C | | - 4.6[b, c] | |
| Pulsed Drain Current | | $I_{DM}$ | - 15 | |
| Continuous Source-Drain Diode Current | $T_C$ = 25 °C | $I_S$ | - 9[a] | |
| | $T_A$ = 25 °C | | - 2[b, c] | |
| Maximum Power Dissipation | $T_C$ = 25 °C | $P_D$ | 13 | W |
| | $T_C$ = 70 °C | | 8.4 | |
| | $T_A$ = 25 °C | | 2.4[b, c] | |
| | $T_A$ = 70 °C | | 1.6[b, c] | |
| Operating Junction and Storage Temperature Range | | $T_J$, $T_{stg}$ | - 55 to 150 | °C |
| Soldering Recommendations (Peak Temperature)[d, e] | | | 260 | |

| THERMAL RESISTANCE RATINGS | | | | | |
|---|---|---|---|---|---|
| **Parameter** | | **Symbol** | **Typical** | **Maximum** | **Unit** |
| Maximum Junction-to-Ambient[b, f] | t ≤ 5 s | $R_{thJA}$ | 41 | 51 | °C/W |
| Maximum Junction-to-Case (Drain) | Steady State | $R_{thJC}$ | 7.5 | 9.5 | |

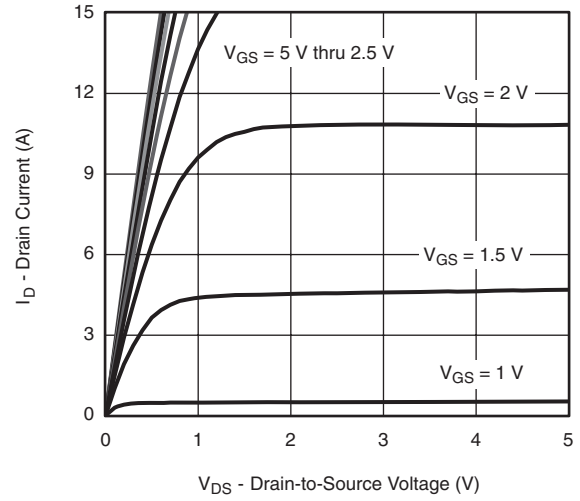
Notes:
a. Package limited.
b. Surface Mounted on 1" x 1" FR4 board.
c. t = 5 s.
d. See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SC-75 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
f. Maximum under Steady State conditions is 105 °C/W.

| **SPECIFICATIONS** $T_J$ = 25 °C, unless otherwise noted | | | | | | |
|---|---|---|---|---|---|---|
| **Parameter** | **Symbol** | **Test Conditions** | **Min.** | **Typ.** | **Max.** | **Unit** |
| **Static** | | | | | | |
| Drain-Source Breakdown Voltage | $V_{DS}$ | $V_{GS}$ = 0 V, $I_D$ = - 250 µA | - 8 | | | V |
| $V_{DS}$ Temperature Coefficient | $\Delta V_{DS}/T_J$ | $I_D$ = - 250 µA | | - 6.1 | | mV/°C |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | 2.1 | | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$, $I_D$ = - 250 µA | - 0.35 | | - 1 | V |
| Gate-Source Leakage | $I_{GSS}$ | $V_{DS}$ = 0 V, $V_{GS}$ = ± 4.5 V | | | ± 100 | µA |
| Zero Gate Voltage Drain Current | $I_{DSS}$ | $V_{DS}$ = - 8 V, $V_{GS}$ = 0 V | | | - 1 | |
| | | $V_{DS}$ = - 8 V, $V_{GS}$ = 0 V, $T_J$ = 55 °C | | | - 10 | |
| On-State Drain Current[a] | $I_{D(on)}$ | $V_{DS} \leq$ - 5 V, $V_{GS}$ = - 4.5 V | - 15 | | | A |
| Drain-Source On-State Resistance[a] | $R_{DS(on)}$ | $V_{GS}$ = - 4.5 V, $I_D$ = - 5.8 A | | 0.042 | 0.058 | Ω |
| | | $V_{GS}$ = - 2.5 V, $I_D$ = - 5.0 A | | 0.058 | 0.080 | |
| | | $V_{GS}$ = - 1.8 V, $I_D$ = - 1.5 A | | 0.081 | 0.100 | |
| | | $V_{GS}$ = - 1.5 V, $I_D$ = - 0.75 A | | 0.096 | 0.130 | |
| | | $V_{GS}$ = - 1.2 V, $I_D$ = - 0.1 A | | 0.150 | 0.250 | |
| Forward Transconductance[a] | $g_{fs}$ | $V_{DS}$ = - 4 V, $I_D$ = - 5.8 A | | 11 | | S |
| **Dynamic[b]** | | | | | | |
| Input Capacitance | $C_{iss}$ | $V_{DS}$ = - 4 V, $V_{GS}$ = 0 V, f = 1 MHz | | 565 | | pF |
| Output Capacitance | $C_{oss}$ | | | 215 | | |
| Reverse Transfer Capacitance | $C_{rss}$ | | | 138 | | |
| Total Gate Charge | $Q_g$ | $V_{DS}$ = - 4 V, $V_{GS}$ = - 5 V, $I_D$ = - 5.8 A | | 8 | 12 | nC |
| | | $V_{DS}$ = - 4 V, $V_{GS}$ = - 4.5 V, $I_D$ = - 5.8 A | | 7.3 | 11 | |
| Gate-Source Charge | $Q_{gs}$ | | | 0.95 | | |
| Gate-Drain Charge | $Q_{gd}$ | | | 1.35 | | |
| Gate Resistance | $R_g$ | f = 1 MHz | 1.9 | 9.5 | 19 | Ω |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD}$ = - 4 V, $R_L$ = 0.87 Ω<br>$I_D \cong$ - 4.6 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 Ω | | 12 | 18 | ns |
| Rise Time | $t_r$ | | | 31 | 46.5 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 30 | 45 | |
| Fall Time | $t_f$ | | | 17 | 26 | |
| **Drain-Source Body Diode Characteristics** | | | | | | |
| Continuous Source-Drain Diode Current | $I_S$ | $T_C$ = 25 °C | | | - 9 | A |
| Pulse Diode Forward Current | $I_{SM}$ | | | | - 15 | |
| Body Diode Voltage | $V_{SD}$ | $I_S$ = - 4.6 A, $V_{GS}$ = 0 V | | - 0.8 | - 1.2 | V |
| Body Diode Reverse Recovery Time | $t_{rr}$ | $I_F$ = - 4.6 A, dI/dt = 100 A/µs, $T_J$ = 25 °C | | 32 | 48 | ns |
| Body Diode Reverse Recovery Charge | $Q_{rr}$ | | | 13 | 20 | nC |
| Reverse Recovery Fall Time | $t_a$ | | | 14 | | ns |
| Reverse Recovery Rise Time | $t_b$ | | | 18 | | |

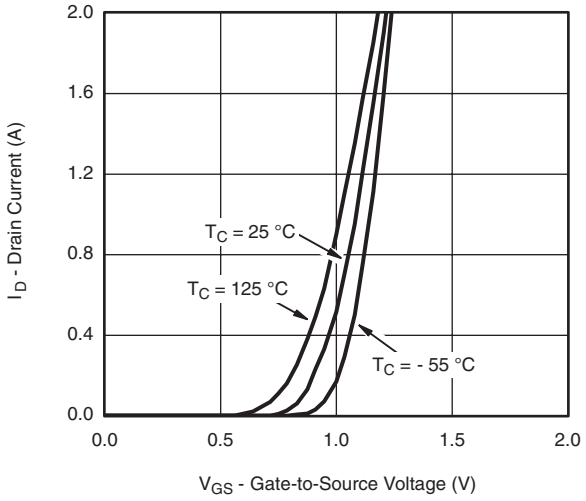
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

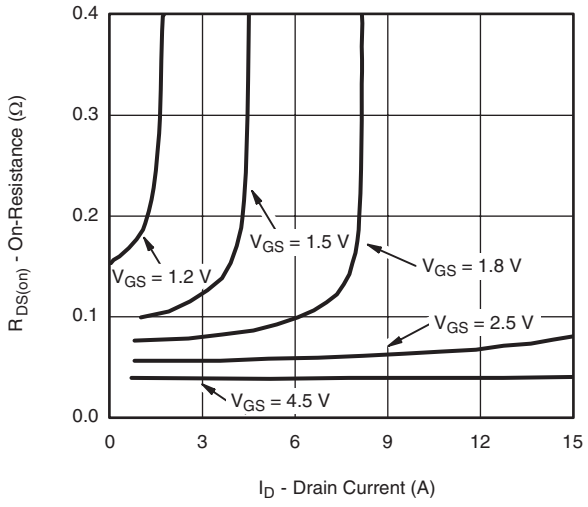
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



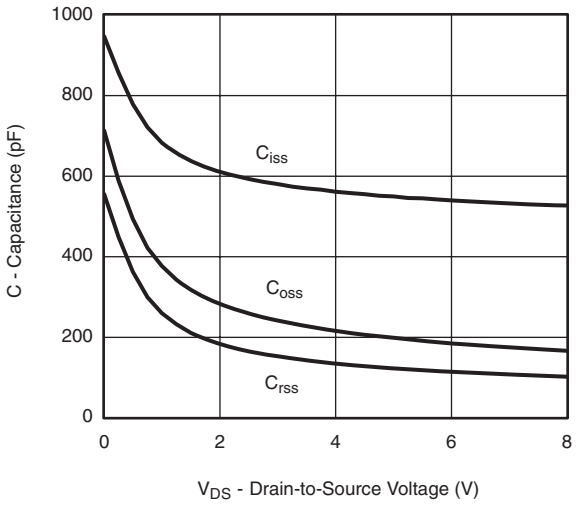

**Output Characteristics**



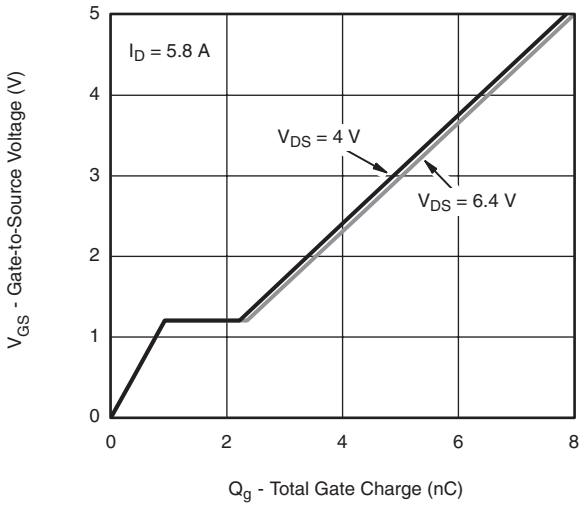

**Transfer Characteristics**



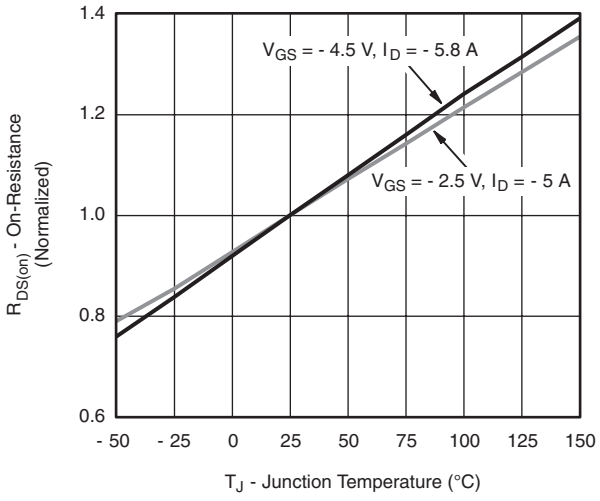

**On-Resistance vs. Drain Current and Gate Voltage**




**Capacitance**

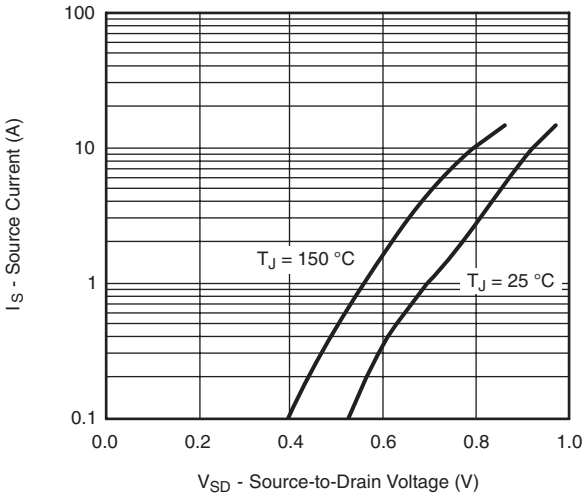



**Gate Charge**

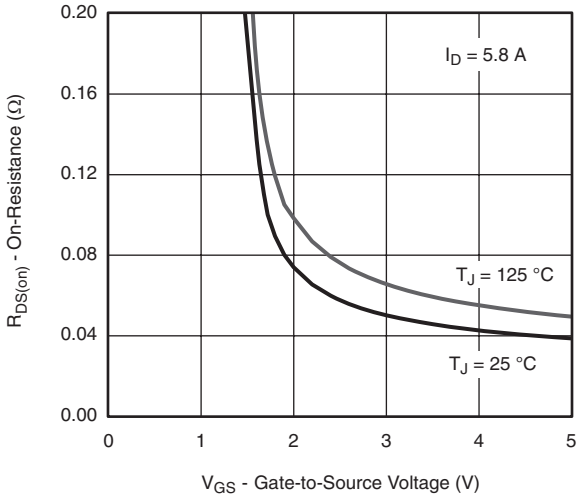



**On-Resistance vs. Junction Temperature**

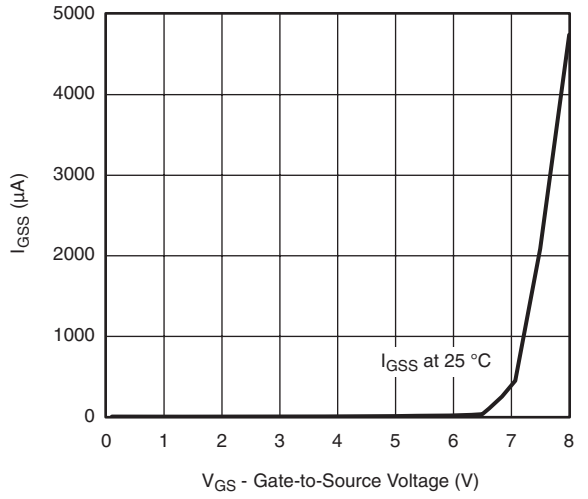
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



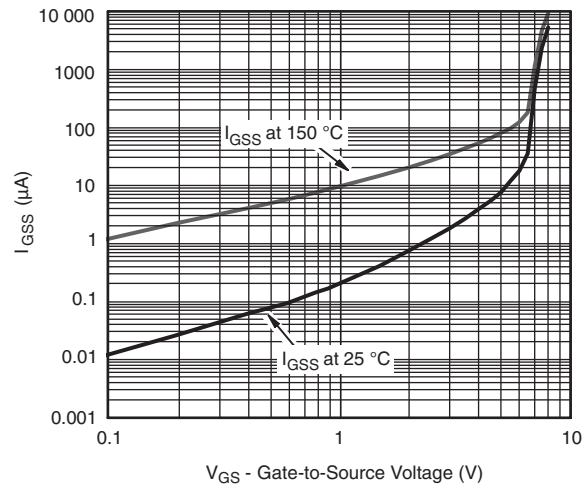

**Soure-Drain Diode Forward Voltage**



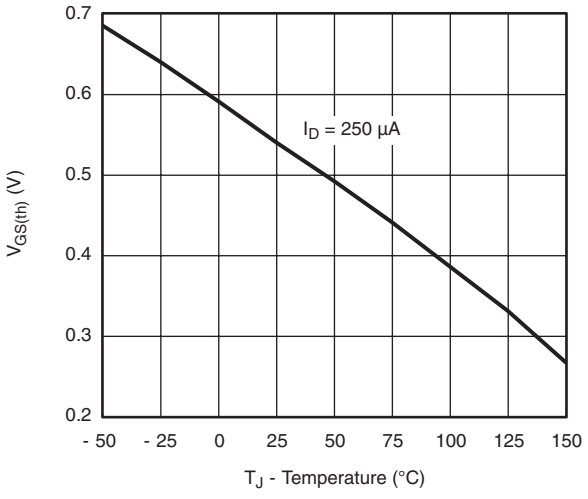

**On-Resistance vs. Gate-to-Source Voltage**



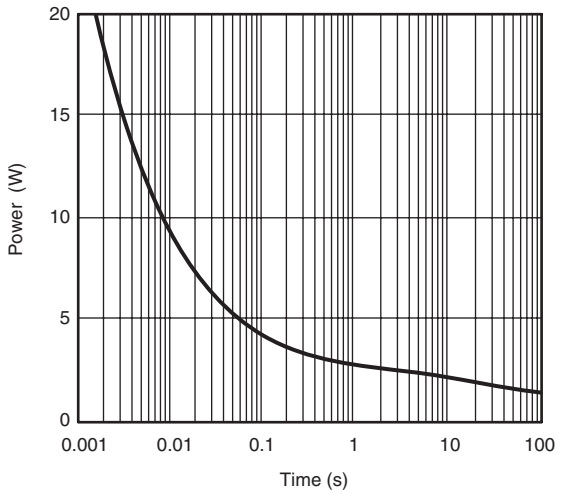

**Gate Source Voltage vs. Gate Current**




**Gate Source Voltage vs. Gate Current**

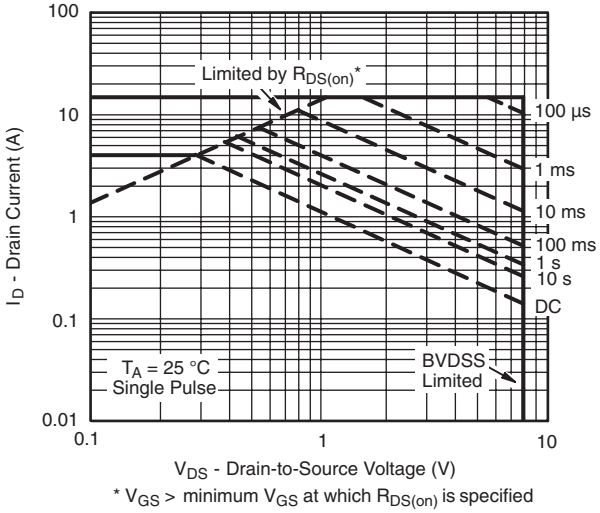



**Threshold Voltage**

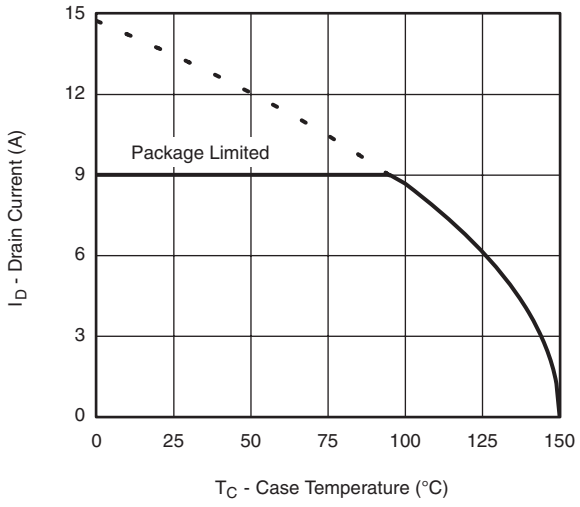



**Single Pulse Power, Junction-to-Ambient**

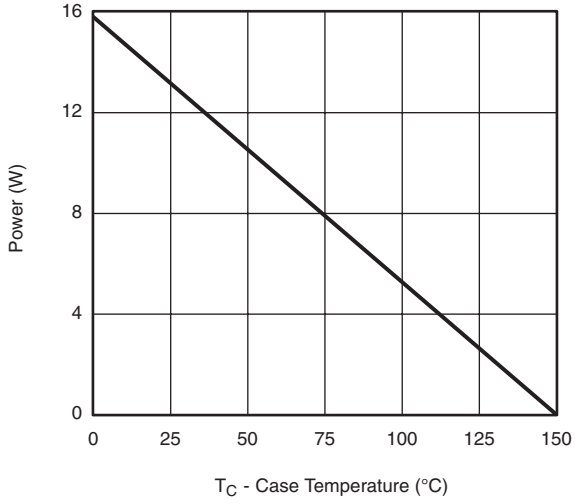
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



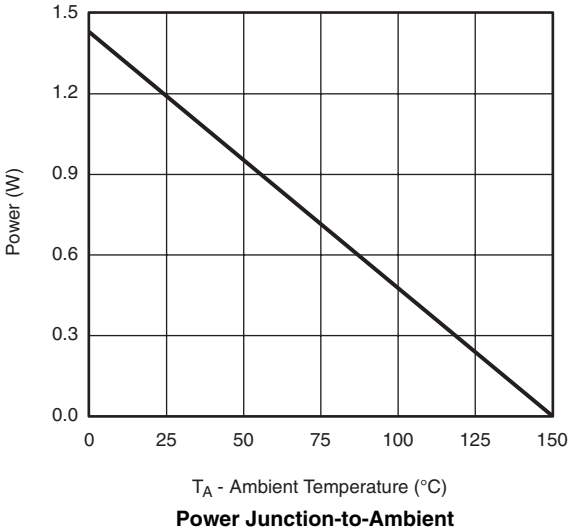

**Safe Operating Area, Junction-to-Case**




**Current Derating****



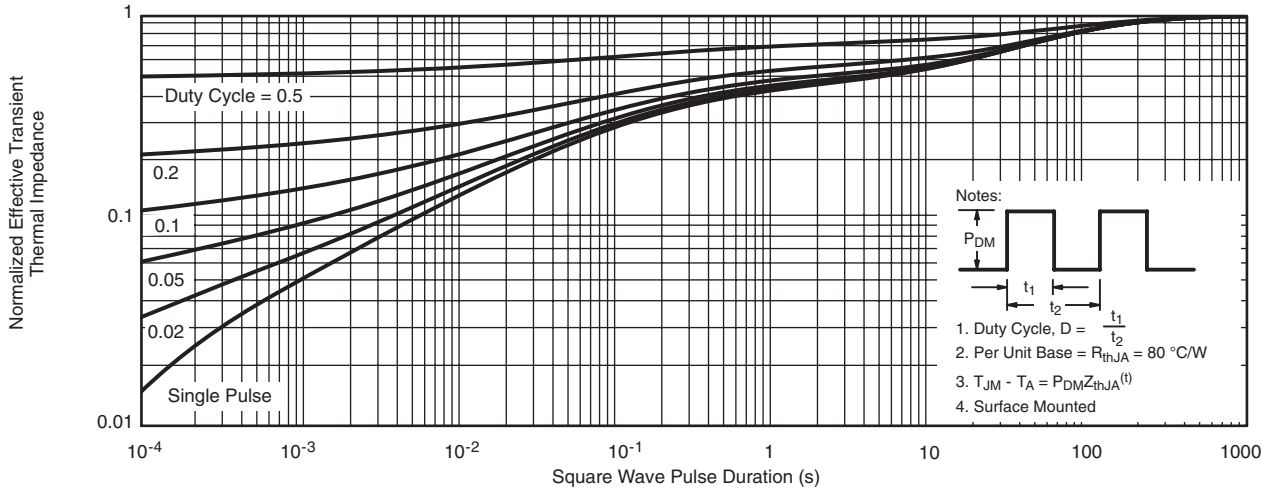

**Power Junction-to-Case**



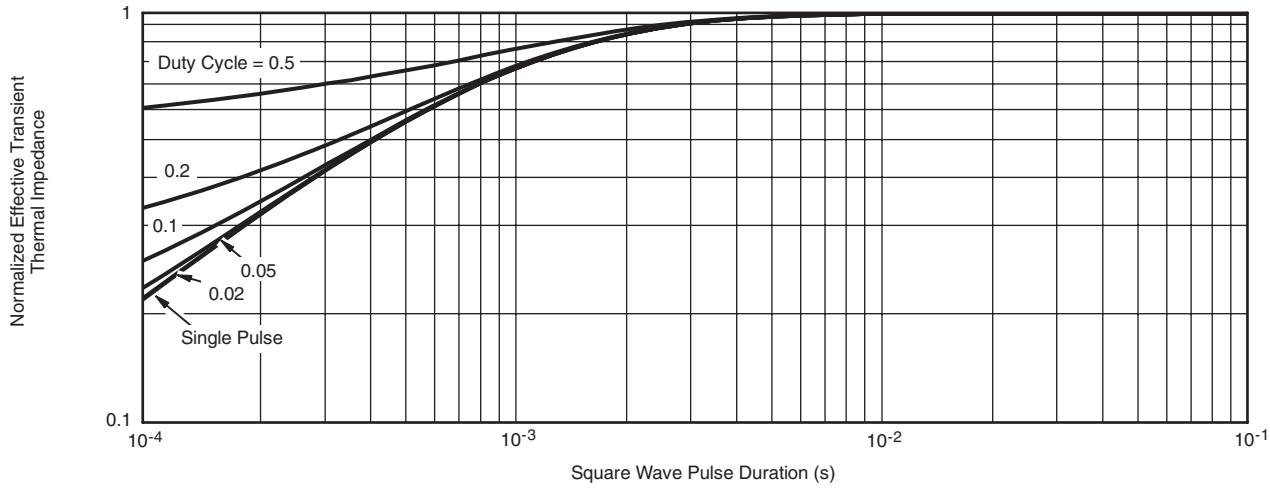

**Power Junction-to-Ambient**

** The power dissipation $P_D$ is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



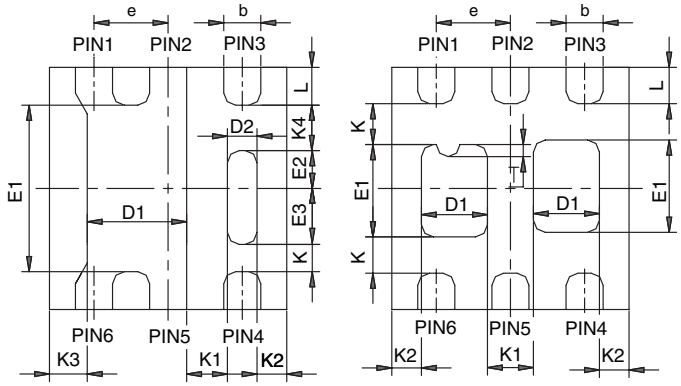

**Normalized Thermal Transient Impedance, Junction-to-Ambient**




**Normalized Thermal Transient Impedance, Junction-to-Case**

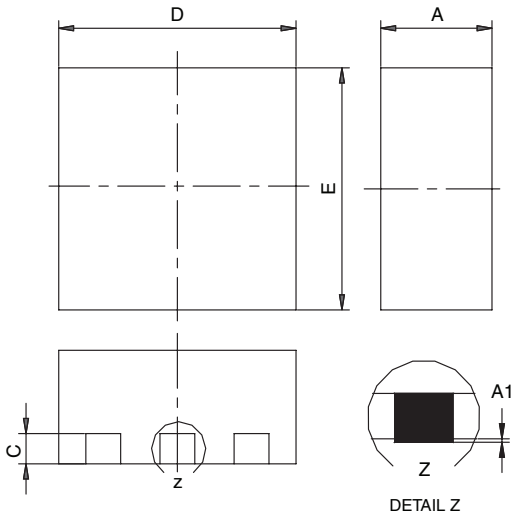
*Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68699.*

## PowerPAK® SC75-6L




BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL



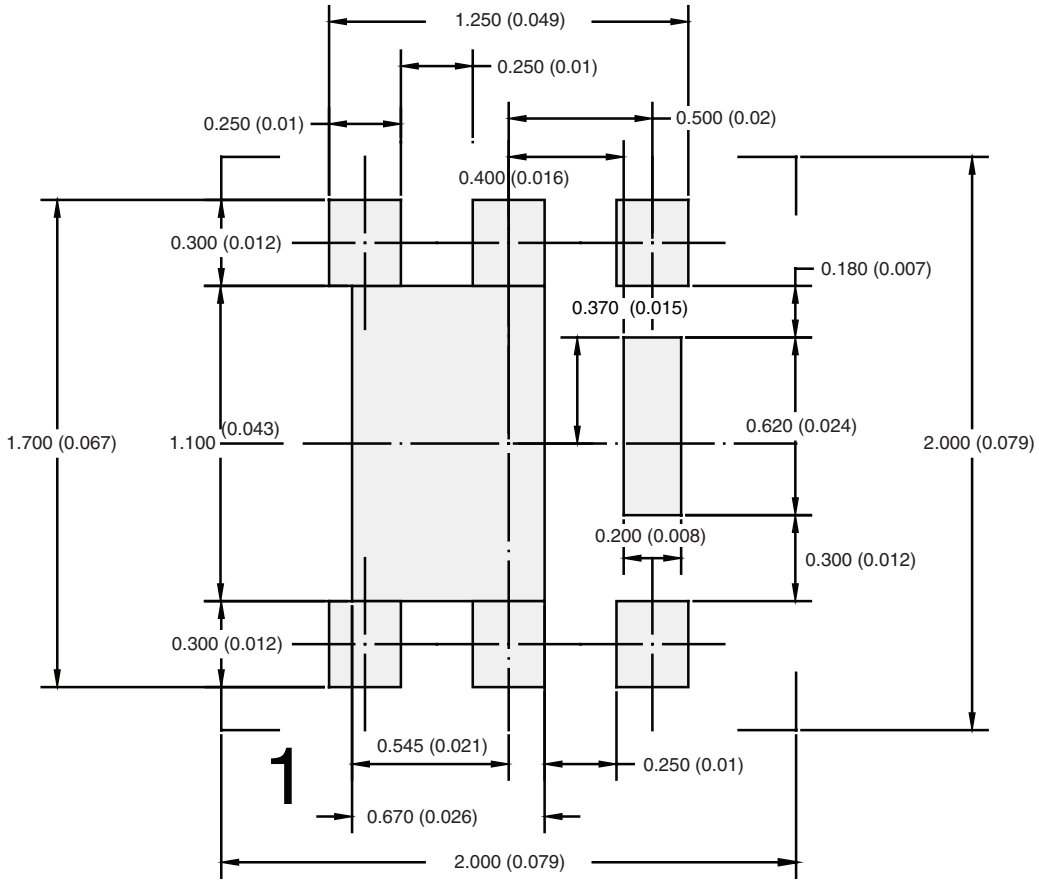

DETAIL Z

Notes:
1. All dimensions are in millimeters
2. Package outline exclusive of mold flash and metal burr
3. Package outline inclusive of plating

| DIM | SINGLE PAD | | | | | | DUAL PAD | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | MILLIMETERS | | | INCHES | | | MILLIMETERS | | | INCHES | | |
| | Min | Nom | Max | Min | Nom | Max | Min | Nom | Max | Min | Nom | Max |
| A | 0.675 | 0.75 | 0.80 | 0.027 | 0.030 | 0.032 | 0.675 | 0.75 | 0.80 | 0.027 | 0.030 | 0.032 |
| A1 | 0 | - | 0.05 | 0 | - | 0.002 | 0 | - | 0.05 | 0 | - | 0.002 |
| b | 0.18 | 0.25 | 0.33 | 0.007 | 0.010 | 0.013 | 0.18 | 0.25 | 0.33 | 0.007 | 0.010 | 0.013 |
| C | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| D | 1.53 | 1.60 | 1.70 | 0.060 | 0.063 | 0.067 | 1.53 | 1.60 | 1.70 | 0.060 | 0.063 | 0.067 |
| D1 | 0.57 | 0.67 | 0.77 | 0.022 | 0.026 | 0.030 | 0.34 | 0.44 | 0.54 | 0.013 | 0.017 | 0.021 |
| D2 | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 | | | | | | |
| E | 1.53 | 1.60 | 1.70 | 0.060 | 0.063 | 0.067 | 1.53 | 1.60 | 1.70 | 0.060 | 0.063 | 0.067 |
| E1 | 1.00 | 1.10 | 1.20 | 0.039 | 0.043 | 0.047 | 0.51 | 0.61 | 0.71 | 0.020 | 0.024 | 0.028 |
| E2 | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 | | | | | | |
| E3 | 0.32 | 0.37 | 0.42 | 0.013 | 0.015 | 0.017 | | | | | | |
| e | 0.50 BSC | | | 0.020 BSC | | | 0.50 BSC | | | 0.020 BSC | | |
| K | 0.180 TYP | | | 0.007 TYP | | | 0.245 TYP | | | 0.010 TYP | | |
| K1 | 0.275 TYP | | | 0.011 TYP | | | 0.320 TYP | | | 0.013 TYP | | |
| K2 | 0.200 TYP | | | 0.008 TYP | | | 0.200 BSC | | | 0.008 TYP | | |
| K3 | 0.255 TYP | | | 0.010 TYP | | | | | | | | |
| K4 | 0.300 TYP | | | 0.012 TYP | | | | | | | | |
| L | 0.15 | 0.25 | 0.35 | 0.006 | 0.010 | 0.014 | 0.15 | 0.25 | 0.35 | 0.006 | 0.010 | 0.014 |
| T | | | | | | | 0.03 | 0.08 | 0.13 | 0.001 | 0.003 | 0.005 |

ECN: C-07431 – Rev. C, 06-Aug-07
DWG: 5935

**RECOMMENDED PAD LAYOUT FOR PowerPAK® SC75-6L Single**




Dimensions in mm/(Inches)

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**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**